

The influence of dopant type and carrier concentration on the effective mass and Seebeck coefficient of GaN_xAs_{1-x} thin films

P. Pichanusakorn,¹ Y. J. Kuang,² C. J. Patel,¹ C. W. Tu,³ and P. R. Bandaru^{1,3,a)}

¹Materials Science Program, Department of Mechanical and Aerospace Engineering, University of California, San Diego, La Jolla, California 92093, USA

²Department of Physics, University of California, San Diego, La Jolla, California 92093, USA

³Department of Electrical and Computer Engineering, University of California, San Diego, La Jolla, California 92093, USA

(Received 16 May 2011; accepted 27 July 2011; published online 18 August 2011)

We probe whether an enhancement in the Seebeck coefficient (S) could be obtained in GaN_xAs_{1-x} through interactions between the N resonant states and the GaAs conduction band. Through experimental investigations, we then determined that an insufficient increase in the density of states effective mass (m_d) precludes such an enhancement. The relative influences of Group IV/VI dopants and the carrier concentration along with N passivation are discussed. © 2011 American Institute of Physics. [doi:10.1063/1.3626041]

It has been recently shown that an enhancement of the Seebeck coefficient (S) may be obtained in PbTe doped with TI due to a resonant interaction between the PbTe conduction band (CB) and the TI energy levels.¹ Such an enhancement then increases the thermoelectric figure of merit, $Z \left(= \frac{S^2 n e \mu}{\kappa} \right)$, where n is the carrier concentration, e is electronic charge, μ is the carrier mobility, and κ the thermal conductivity. We were then motivated by the possible application of this concept to the “highly mismatched alloy” systems,² such as N-doped GaAs, i.e., GaN_xAs_{1-x}, where resonant interactions between the N energy levels and the GaAs CB are prevalent. Such interactions, as described by the band anti-crossing (BAC) model, involved a splitting of the GaAs CB, which drastically reduced the electronic energy band gap but increased the effective mass, m_d , due to the decreased band curvature of the lower split-off branch (the E_- band).³ The increased m_d then enhances S at a given n , as is evident through the following relations derived⁴⁻⁶ from the Boltzmann transport equation, assuming parabolic band structure and a relaxation time approximation, i.e., $\tau(E) = \tau_0 E^r$ where τ_0 and r are scattering constants (e.g., $r = -0.5$ for strong localized nitrogen impurity scattering,⁷⁻⁹ $r = 1.5$ for weakly screened ionized impurity etc.¹⁰)

$$n = \frac{1}{2\pi^2} \left(\frac{2k_B T m_d}{\hbar^2} \right)^{3/2} [F_{1/2}(\eta)], \quad (1)$$

$$S = \mp \frac{k_B}{e} \left[\frac{\left(r + \frac{5}{2} \right) F_{r+3/2}(\eta)}{\left(r + \frac{3}{2} \right) F_{r+1/2}(\eta)} - \eta \right]. \quad (2)$$

In the above, k_B and \hbar are the Boltzmann and reduced Planck constants, T is temperature, $\eta = \frac{E_F}{k_B T}$ is the reduced Fermi energy, where E_F is the Fermi energy as measured from the

CB minimum, and $F_j(\eta) = \int_0^\infty \frac{x^j}{e^{(x-\eta)+1}} dx$ is the j th order Fermi integral, which is always positive and increases with η and j . It is then seen that as η is increased (/decreased), this yields an increase (/decrease) of the n and a decrease (/increase) of the $|S|$. Such a contrary relationship then dictates an optimal value for η for maximizing the power factor, $S^2 \sigma$.⁴ However, if m_d is increased, e.g., by the addition of N, while n is held constant, η would be reduced with an accompanying enhancement of the $|S|$. Additionally, increasing r would also increase $|S|$.⁴

While N doping is expected to enhance m_d and $|S|$, conventional carrier doping of GaAs, say, with Group IV (e.g., Si) or Group VI (e.g., Te, Se) elements should increase n , with minimal impact on the band structure and the m_d . However, while Te-doped GaN_xAs_{1-x} have shown an increase in m_d ,⁸ there was a decrease in m_d instead⁹ in Se-doped samples. Additionally, mutual passivation of N and Group IV elements could reduce the effective number of N resonant states, thus weakening or even reversing the BAC effects through an increased band gap and a loss of donor contributed n .¹¹ Such passivation occurs when Si atoms which occupy the Ga lattice sites (Si_{Ga}) bond with Nitrogen on Arsenic site (N_{As}). On the contrary, direct bonding with N_{As} is unlikely with Group VI elements which only occupy the As sites. While isolated N impurities could contribute to resonant energy levels within the host CB, N aggregates could also form *cluster states* with localized energy levels deep within the GaAs bandgap. In the linear combination of isolated nitrogen resonant states (LCINS) framework, such cluster states could yet interact with the E_- band if the band minimum is sufficiently lowered,¹²⁻¹⁴ and may also lead to m_d enhancement. Since Si is a common dopant for GaAs, it is important to verify whether Si-N passivation would impact the expected enhancement of m_d and S in GaN_xAs_{1-x}. In this paper, we aim to investigate such a possible increase of S in Si-doped GaN_xAs_{1-x} thin films over a range of N content (from $x = 0$ to 0.025) with $n \sim 4-9 \times 10^{17} \text{ cm}^{-3}$.

GaN_xAs_{1-x} thin films (~ 200 nm thick) were fabricated on semi-insulating (100) GaAs substrates through molecular beam epitaxy. The substrates were initially heated to 580 °C

^{a)}Author to whom correspondence should be addressed. Electronic mail: pbandaru@ucsd.edu

to desorb native oxide, and a 200 nm GaAs buffer layer was grown to reduce surface roughness. The substrate temperature was then lowered to ~ 500 °C during the growth of the active $\text{GaN}_x\text{As}_{1-x}$ layer, using elemental Ga and thermally cracked As_2 (from AsH_3), and N injected from a radical beam source. Si was injected through thermal evaporation. The temperature of the Si source (T_{Si}) was varied to modulate the carrier concentration, n . The growth rate for the buffer and active layer was ~ 0.2 nm/s. The N concentration was estimated from the determined (using x-ray diffraction) film lattice parameters assuming a linear dependence (Vegard's law) between the lattice parameters of GaAs and GaN. The N concentration so estimated has been shown to be comparable to that determined by techniques such as secondary ion mass spectroscopy (SIMS),¹⁵ for $x < 0.030$.¹⁶ However, while the N as determined by SIMS and XRD may be comparable, the *effective* N concentration that actually contributes to effective mass/band gap reduction could be smaller, e.g., due to the formation of cluster states. For example, non-equilibrium synthesis of $\text{GaN}_x\text{As}_{1-x}$ (e.g., using pulsed laser melting combined with rapid thermal annealing) has indicated a greater bandgap reduction compared to conventional thin film growth.^{15,17} Additionally, ballistic electron emission microscopy photocurrent spectroscopy, and photoresponsivity could be used to measure the effective N concentration.

Patterned electrodes (constituted of Ge/Ni/Au layers of 20/20/100 nm thickness) were deposited, by electron beam evaporation, onto the film to serve as voltage, current, and temperature probes (in the four-wire configuration) for electrical conductivity (ρ) and S measurements.¹⁸ It was necessary to anneal the samples at 450 °C in N_2 gas for reliable Ohmic contacts. The n was determined from Hall coefficient measurements (in a magnetic field of 0.24 T), while S was calculated from the voltage versus temperature difference (ΔT) slope. The ΔT were calibrated through the electrical resistance variation and the measured temperature coefficient of resistance. The accuracy of our measurements was consistent with a number of previous studies,^{8,9,19,20} as indicated in Figure 1. Comparison with calculations of Eqs. (1) and (2)

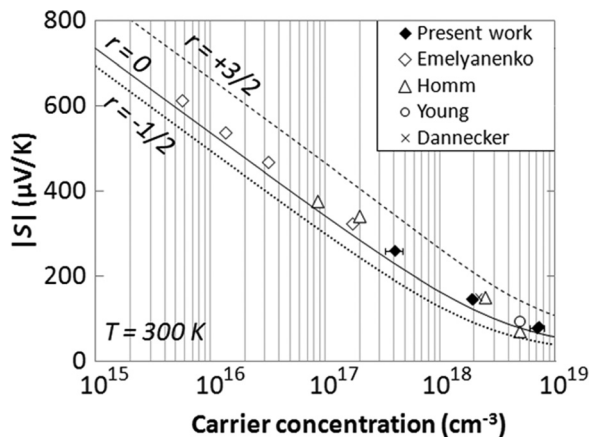


FIG. 1. Seebeck coefficient, S vs. carrier concentration, n , of GaAs as measured in this work and compared to that of Emelyanenko *et al.* (see Ref. 19), Homm *et al.* (see Ref. 20), Young *et al.* (see Ref. 9), and Dannecker *et al.* (see Ref. 8). Calculated values assuming various r values are indicated through lines.

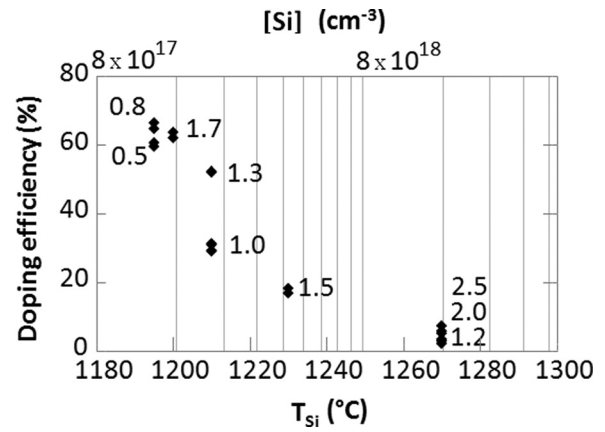


FIG. 2. Doping efficiency vs Si cell temperature, T_{Si} . The extrapolated Si concentration, N_{Si} is shown on the top axis. The numbers, next to the data points, indicate the N content (x in % in $\text{GaN}_x\text{As}_{1-x}$). The $n \sim 4\text{--}9 \times 10^{17}$ cm^{-3} for all the samples.

suggested that r should be slightly greater than 0 for GaAs (e.g., previous measurements⁹ suggest $r \sim 0.26$), which seems appropriate for polar optical phonon scattering¹⁰ prevalent in III-V semiconductors at room temperature.²¹ The increase in m_d of GaAs from 0.067 to 0.090 m_o , as n increases from 10^{16} to 10^{19} cm^{-3} , due to CB non-parabolicity,²² was also considered.

We now report on the measurements of $\text{GaN}_x\text{As}_{1-x}$. We define a *doping efficiency* as the percentage ratio of the measured n in the $\text{GaN}_x\text{As}_{1-x}$ films to the Si concentration: $[\text{Si}]$ —estimated from the n measured in nitrogen-free GaAs, assuming $[\text{Si}] \approx n$. Such assumption neglects the Si donor (Si_{Ga}) compensation by Si acceptors (situated on As lattice sites: Si_{As}). However, $[\text{Si}]$ may not be much underestimated, as we observed that: (a) the n in GaAs increased exponentially with T_{Si} with no saturation/reduction and (b) the maximum obtained n of 9×10^{18} cm^{-3} coincides with the $\sim 30\%$ compensation of Si_{Ga} by Si_{As} .²³ Regardless, the reduction of doping efficiency (to 2%–70% seen in Figure 2) seems to be due to N incorporation. The low efficiency was surprising because, unlike compensation by Si_{As} (which could be long-range), Si-N passivation requires Si to be adjacent to N, which should be rare given the low concentration of both N and Si. It was then probable that the spatial

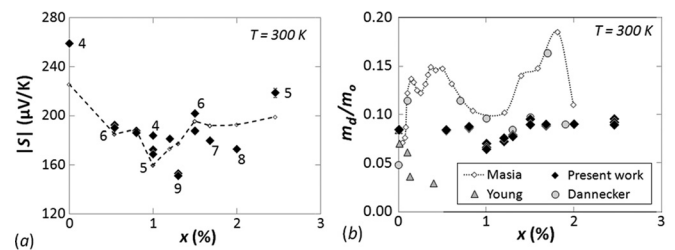


FIG. 3. (a) The Seebeck coefficient variation with percent nitrogen (x in %) in $\text{GaN}_x\text{As}_{1-x}$. The numbers, next to the data points, indicate n in units of 10^{17} cm^{-3} . The dotted line indicate the extrapolation of S to $n = 6 \times 10^{17}$ cm^{-3} . (b) The density of states effective mass (m_d , as a fraction of the free electron effective mass, m_o) as measured in this work, compared to literature, i.e., Young *et al.* (see Ref. 9), Dannecker *et al.* (see Ref. 8), and LCINS model based calculations by Masia *et al.* (see Ref. 14). The error bar for our data is invisible at this scale, while that for Dannecker *et al.*'s data, the error bars ($= \pm 0.019$) were omitted for clarity.

distribution of Si and N is not random, but maybe influenced, e.g., by Coulombic attraction between Si and N. Hall measurements on *pre*- and *post*-450°C annealed samples indicate that much passivation occurred during growth. Extensive Si-N passivation was seen previously,²⁴ but was not observed when Si was ion-implanted *post*-growth, and annealing >600°C was required to stimulate passivation through Si diffusion.¹¹ The observed decrease (increase) in doping efficiency (passivation) with increasing x and T_{Si} or [Si] may be due to an enhanced surface diffusivity of Si adatoms.

A lower $|S|$ was generally observed with increasing N concentration, as shown in Figure 3(a). For comparison, we calculated the $|S|$ at a particular $n = 6 \times 10^{17} \text{ cm}^{-3}$ (chosen to coincide with the average carrier concentration in our samples, and to compare with literature⁸) with m_d values determined from experimentally measured n and S . The m_d —Figure 3(b), was calculated from Eq. (1), with a given n and T , and the η deduced from Eq. (2) and S . While $r = 0$ is assumed for GaAs, for $\text{GaN}_x\text{As}_{1-x}$, the r was reduced to -0.5 , corresponding to previous measurements⁹/assumptions.⁸ We note that the $|S|$ initially decreased significantly in the $x = 0$ to 0.005 range, but then increased slightly before exhibiting a minimum at $\sim x = 0.01$. In term of the m_d variation, there seemed to be intriguing similarities and differences between our data and literature, e.g., the minimum at $x = 0.01$ —Figure 3(b) predicted by the LCINS model.⁸ However, our observed variation seems to be closer to the BAC model. The differences between our results and Dannecker *et al.*⁸ could be related to their use of Te as the dopant. On the other hand, Young *et al.*⁹ seem to observe an entirely opposite trend, see Figure 3(b), in Se doped $\text{GaN}_x\text{As}_{1-x}$ samples (with higher $n \sim 6 \times 10^{18} \text{ cm}^{-3}$), where a diminished m_d was attributed to band gap reduction as explained through k-p theory.⁹

From the BAC model, as N concentration is increased, the E_c band should flatten and sweep into the band gap, with concomitant resonant interactions with *cluster states* from N aggregates (as specified through the LCINS model^{12–14}). Such interactions may then produce an even greater increase in m_d . For example, the m_d maxima at $x = 0.003$ and $x = 0.005$ in Figure 3(b) were attributed to interaction with N-Ga-N and N-Ga-N-Ga-N clusters, respectively. Correspondingly, the close relationship of the m_d to the BAC model predicted variation could indicate the absence of such interactions. While passivation has been described in term of bonding of single Si_{Ga} to single N_{As} , it is conceivable that Si could also replace Ga in N-Ga-N constituted clusters. Additionally, Si could be more strongly attracted, through Coulomb interactions, to larger N aggregates compared to single N, leading to a disproportionate passivation of the former. Considering that the dramatic increase in m_d predicted by the LCINS model is due to N-Ga-N aggregates whose concentration “is expected to be only a small fraction of total N concentration,”¹³ the passivation of such aggregates and the corresponding decrease in effective N clusters could dampen m_d enhancement as observed in our work. Since mutual Si-N

passivation is not observed for Group VI elements, similar behavior is unlikely in Se^9/Te^8 doped samples. However, it is possible, that a pronounced m_d modulation could yet be observed in Si-doped $\text{GaN}_x\text{As}_{1-x}$, if Si-N passivation is avoided, say, through doping by *post*-growth ion-implantation.

In conclusion, we observed that the addition of N to Si-doped $\text{GaN}_x\text{As}_{1-x}$ ($x = 0.005–0.025$) did not lead to an expected increase in S , due to insufficient increase of the m_d . However, we found an intriguing dependence of the m_d on N concentration that differs in scale, but not in trend, from the LCINS model. We propose the possibility that Si-N passivation may play a role in disrupting formation of N-Ga-N aggregates, leading to dampened m_d by N cluster states.

We gratefully acknowledge support from the National Science Foundation (Grant ECS-05-08514).

- ¹J. P. Heremans, V. Jovic, E. S. Toberer, A. Saramat, K. Kurosaki, A. Charoenphakdee, S. Yamanaka, and G. J. Snyder, *Science* **321**, 554 (2008).
- ²J.-H. Lee, J. Wu, and J. C. Grossman, *Phys. Rev. Lett.* **104**, 016602 (2010).
- ³W. Shan, W. Walukiewicz, J. W. Ager, E. E. Haller, J. F. Geisz, D. J. Friedman, J. M. Olson, and S. R. Kurtz, *Phys. Rev. Lett.* **82**, 1221 (1999).
- ⁴P. Pichanusakorn and P. Bandaru, *Appl. Phys. Lett.* **94**, 223108 (2009).
- ⁵P. Pichanusakorn and P. Bandaru, *J. Appl. Phys.* **107**, 074304 (2010).
- ⁶P. Pichanusakorn and P. Bandaru, *Mater. Sci. Eng. R.* **67**, 19 (2010).
- ⁷S. Fahy, A. Lindsay, H. Ouerdane, and E. P. O'Reilly, *Phys. Rev. B* **74**, 035203 (2006).
- ⁸T. Dannecker, Y. Jin, H. Cheng, C. F. Gorman, J. Buckeridge, C. Uher, S. Fahy, C. Kurdak, and R. S. Goldman, *Phys. Rev. B* **82**, 125203 (2010).
- ⁹D. L. Young, J. F. Geisz, and T. J. Coutts, *Appl. Phys. Lett.* **82**, 1236 (2003).
- ¹⁰M. Lundstrom, *Fundamentals of carrier transport*, 2nd ed. (Cambridge University Press, Cambridge, 2000).
- ¹¹K. M. Yu, W. Walukiewicz, J. Wu, D. E. Mars, D. R. Chamberlin, M. A. Scarpulla, O. D. Dubon, and J. F. Geisz, *Nature Mater.* **1**, 185 (2002).
- ¹²A. Lindsay and E. P. O'Reilly, *Phys. Rev. Lett.* **93**, 196402 (2004).
- ¹³P. R. C. Kent and A. Zunger, *Phys. Rev. B* **64**, 115208 (2001).
- ¹⁴F. Masia, G. Pettinari, A. Polimeni, M. Felici, A. Miriametro, M. Capizzi, A. Lindsay, S. B. Healy, E. P. O'Reilly, A. Cristofoli, G. Bais, M. Piccin, S. Rubini, F. Martelli, A. Franciosi, P. J. Klar, K. Volz, and W. Stolz, *Phys. Rev. B* **73**, 073201 (2006).
- ¹⁵T. Kim, K. Alberi, O. D. Dubon, M. J. Aziz, and V. Narayanamurti, *J. Appl. Phys.* **104**, 113722 (2008).
- ¹⁶W. J. Fan, S. F. Yoon, T. K. Ng, S. Z. Wang, W. K. Loke, R. Liu, and A. Wee, *Appl. Phys. Lett.* **80**, 4136 (2002).
- ¹⁷W. Yi, T. Kim, I. Shalish, M. Loncar, M. J. Aziz, and V. Narayanamurti, *Appl. Phys. Lett.* **97**, 151103 (2010).
- ¹⁸A. I. Boukai, Y. Bunimovich, J. Tahir-Kheli, J.-K. Yu, W. A. Goddard III, and J. R. Heath, *Nature* **451**, 168 (2008).
- ¹⁹O. V. Emelyanenko, D. N. Nasledov, V. G. Sidorov, V. A. Skripkin, and G. N. Talalakin, *Phys. Status Solidi* **12**, K93 (1965).
- ²⁰G. Homm, P. J. Klar, J. Teubert, and W. Heimbrodt, *Appl. Phys. Lett.* **93**, 042107 (2008).
- ²¹M. P. Vaughan and B. K. Ridley, in *Dilute III-V Nitride Semiconductors and Material Systems*, edited by A. Erol (Springer, Berlin, Heidelberg, 2008), Vol. 105, p. 255–281.
- ²²A. Raymond, J. L. Robert, and C. Bernard, *J. Phys. C* **12**, 2289 (1979).
- ²³S. Schuppler, D. L. Adler, L. N. Pfeiffer, K. W. West, E. E. Chaban, and P. H. Citrin, *Appl. Phys. Lett.* **63**, 2357 (1993).
- ²⁴Y. Jin, Y. He, H. Cheng, R. M. Jock, T. Dannecker, M. Reason, A. M. Mintairov, C. Kurdak, J. L. Merz, and R. S. Goldman, *Appl. Phys. Lett.* **95**, 092109 (2009).